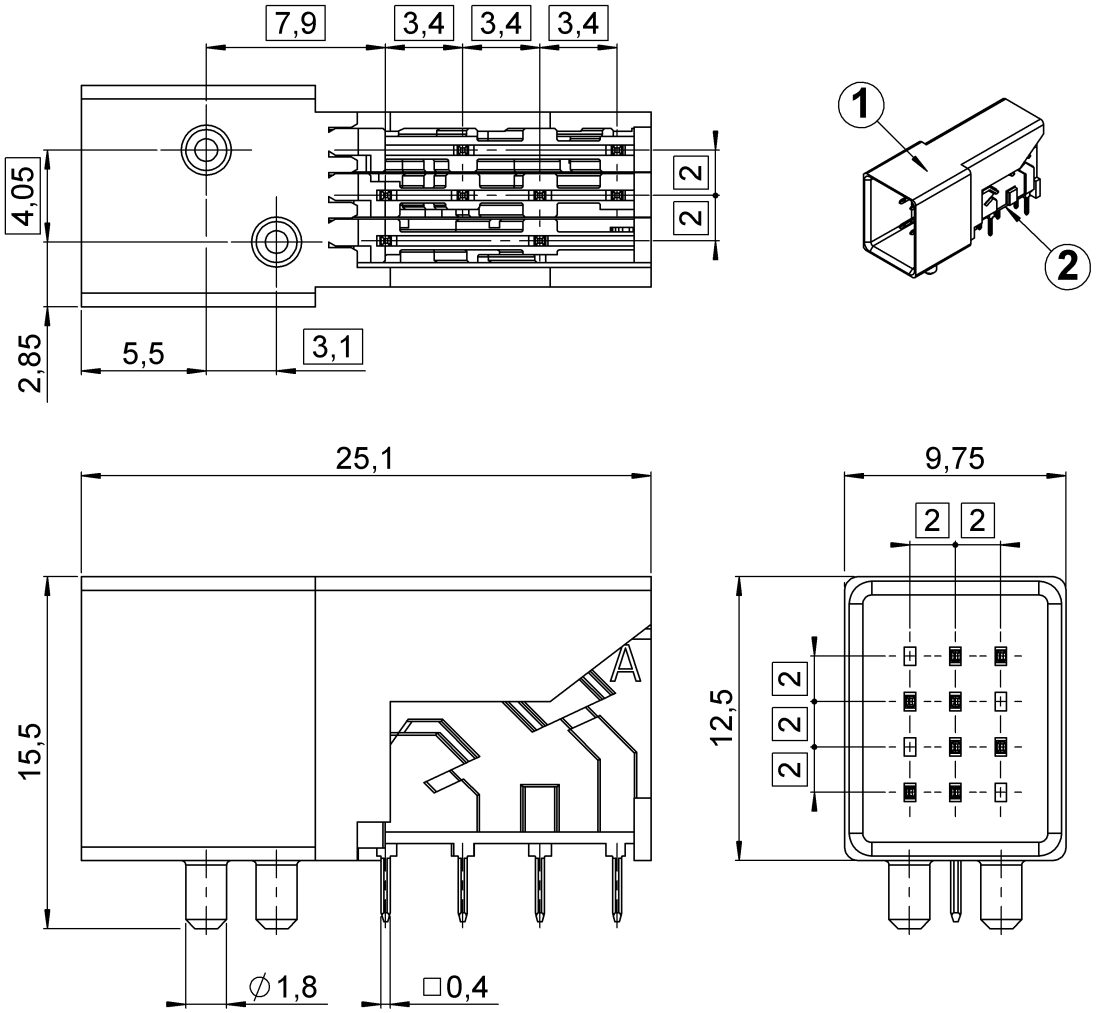
| PAGE **1/7** | ISSUE **12-02-16A** | SERIES **OCTIS** | PART NUMBER **OCTI460500** |
|---|---|---|---|




All dimensions are in mm.

**DESCRIPTION**

| REP | COMPONENT | MATERIALS | PLATING |
|---|---|---|---|
| 1 | **Housing** | **PLASTIC** | **-** |
| 2 | **Contact** | **COPPER ALLOY** | **SN** |

## GENERAL CHARACTERISTICS

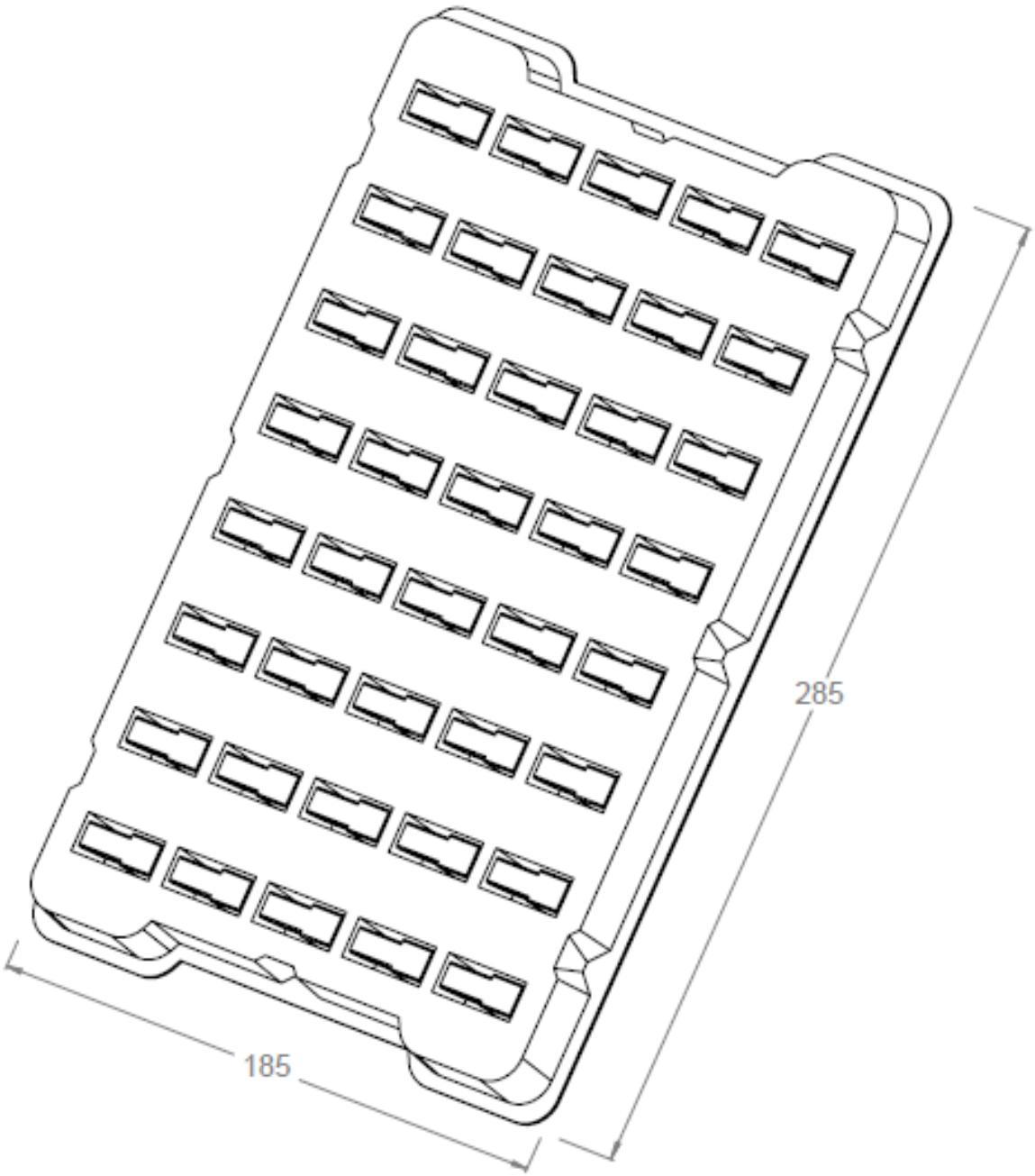
| | | |
|---|---|---|
| **Mechanical** | | |
| Mating endurance (cycles) | IEC 61300-2-2 | 100 |
| Axial Tensile load (N min) | IEC 61300-2-4 | - |
| Vibration | EIA 364-28 | - |
| Weight (g) | - | 1,3440 |
| **Environmental** | | |
| Protection class (mated condition) | IEC 60529 | (*) |
| Operating temperature (°C) | IEC 61300-2-22 | -40 / +85 |
| Storage temperature (°C) | IEC 61300-2-22 | -40 / +85 |
| RoHS | - | Compliant |
| Flammability | UL 94 | V0 |
| **Electrical** | | |
| Working voltage | - | Max. 300V AC (r.m.s.) |
| Insulation resistance | EIA 364-21C | 5000MΩ minimum |
| Dielectric withstanding voltage | EIA 364-20C | (To be tested) |
| **Others** | | |
| Packaging | - | Packaging in Hot Formed Tray |

(*) Mated condition

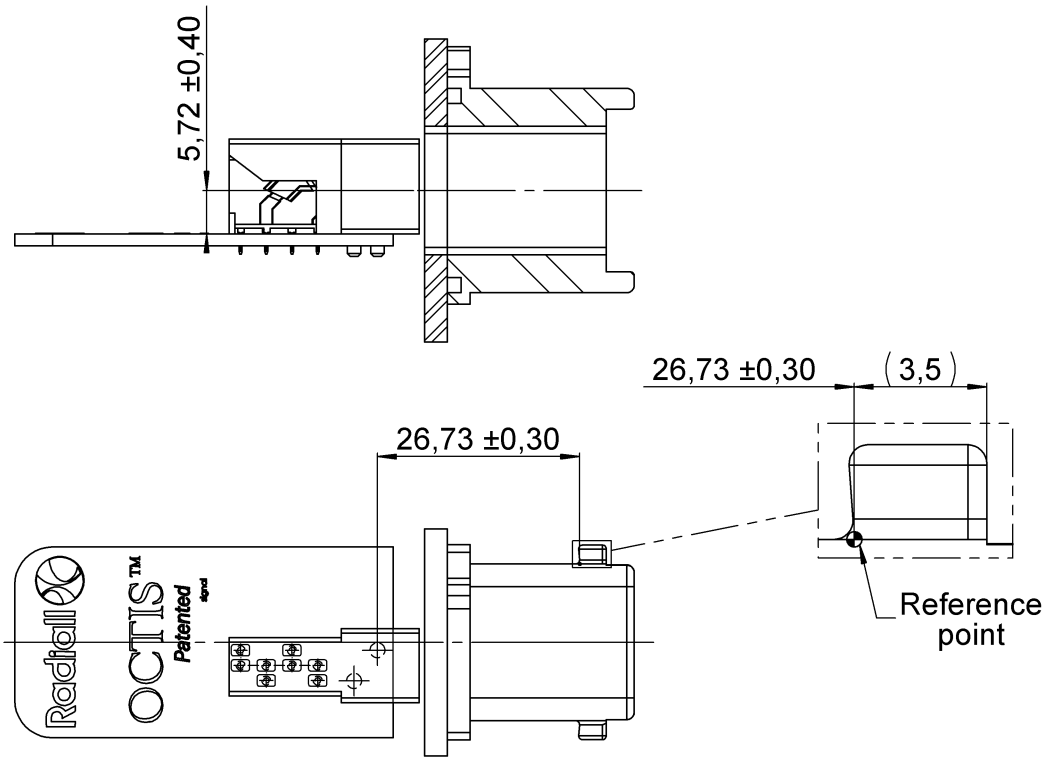
**PACKAGING**

**Packaging in Hot Formed Tray**

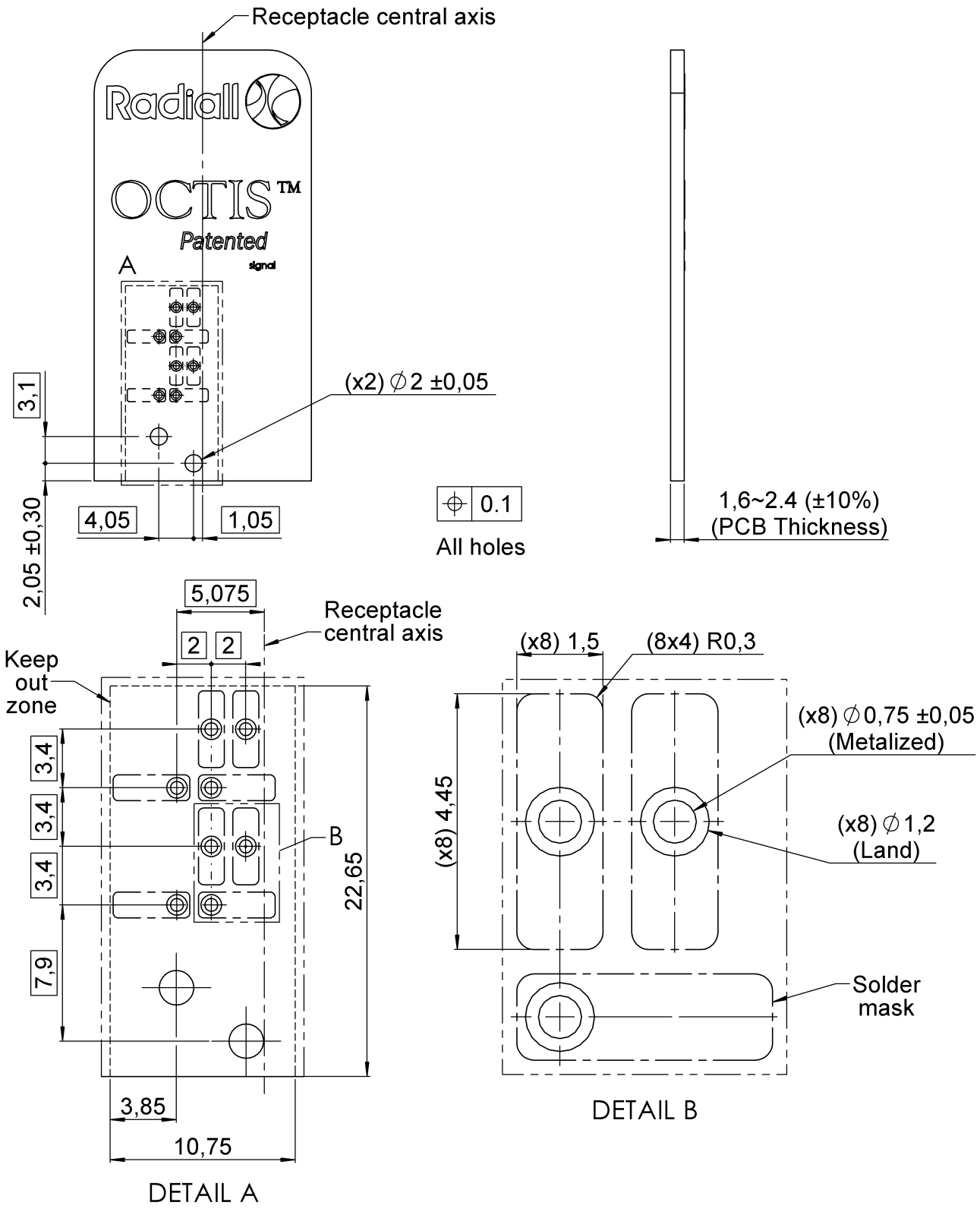
**(In progress, must be defined with our supplier)**



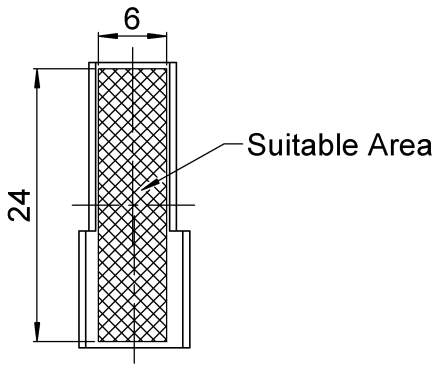
## POSITIONING AND PATTERN DEFINITION



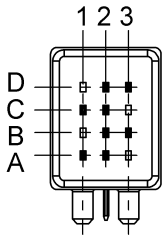
**FOOT/PRINT (General tolerance for PCB ±0.1 mm)**



## SUITABLE AREA FOR PICK & PLACE VACUUM NOZZLE




## CONTACTS CONFIGURATION



## SOLDER PROCEDURE*

1. Deposit solder paste (Sn Ag4 Cu0.5) on solder pads / mounting area by screen printing application. We recommend a low residue flux. Verify that the edges of the pads are clean.

2. Place the component on the mounting area with a pick & place machine.
   A video camera is recommended for a good positioning of the component.
   Adhesive agents must not be used on the component.

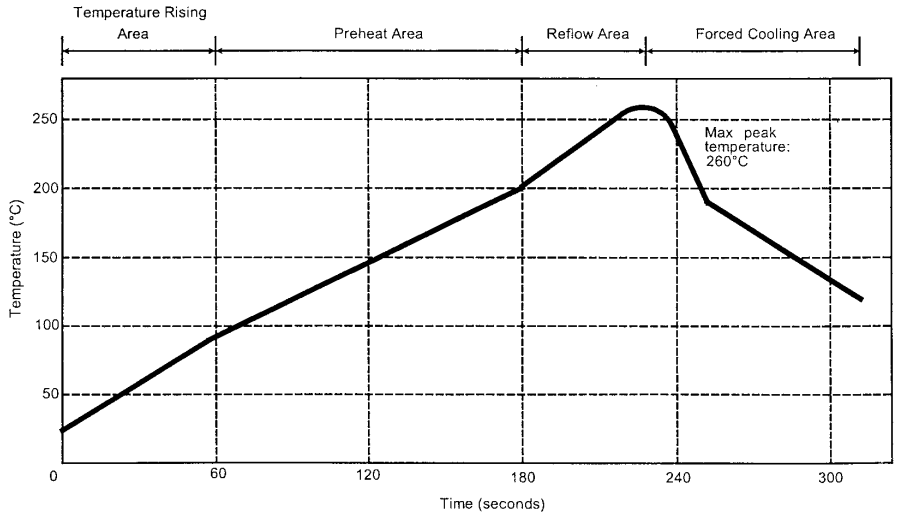
3. This process of soldering has been tested with a convection oven.
   Below please find the typical soldering profile to use.

4. Optional cleaning of printed circuit board.

5. Check solder joints and position of the component by visual inspection.

Note: When soldering a receptacle, no plug should be mated to the receptacle before completion of this procedure.

## TEMPERATURE PROFILE




| Parameter | Value | Unit |
|---|---|---|
| Temperature rising Area | 1 to 4 | °C/sec |
| Max Peak Temperature | 260 | °C |
| Max dwell time @260°C | 10 | sec |
| Min dwell time @235°C | 20 | sec |
| Max dwell time @235°C | 60 | sec |
| Temperature drop in cooling Area | -1 to - 4 | °C/sec |
| Max dwell time above 100°C | 420 | sec |

* Typical data for reflow process. Alternatively, wave soldering is also possible

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